

■ Features

- This filter is characterized by small size, highly effective in noise suppression.
- High common mode impedance at noise band and low differential mode impedance at signal band. Due to the low differential mode impedance with high coupling factor, there is almost no distortion on high speed transmission of high resolution video signals.

■ Applications

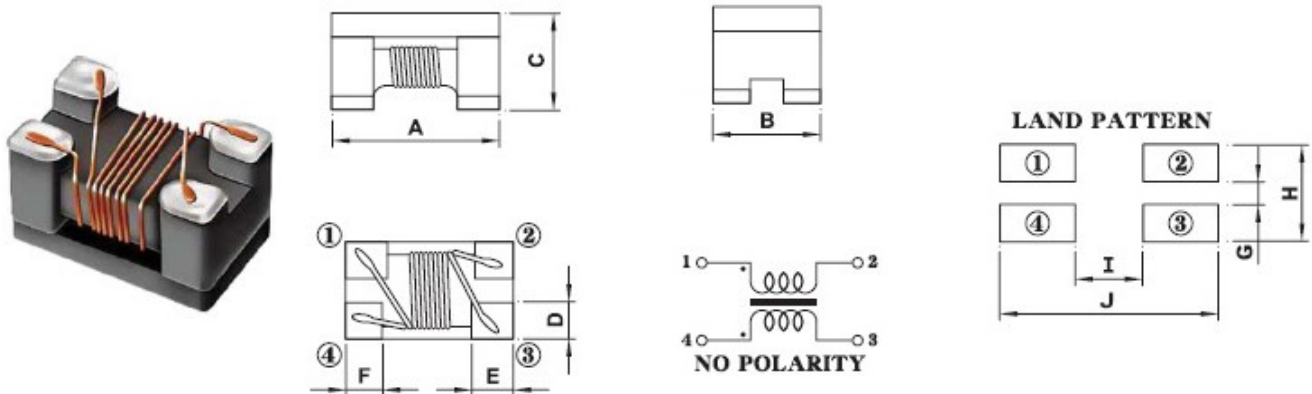
- YLM Series is suited for use on the USB2.0 line and IEEE1394 line of Notebook PC, LVDS lines of PC, LCD Monitor, PCI express, small digital AV equipment such as digital Camera and Free disk, MP3 player and Serial-ATA.

■ Product Identification

$\frac{\text{YLM}}{(1)}$ $\frac{\square\square\square\square}{(2)}$ $\frac{\square}{(3)} - \frac{\square\square\square}{(4)}$ $\frac{\text{T}}{(5)}$

- (1) : Type
- (2) : Dimensions
- (3) : Identification Code
- (4) : Impedance
- (5) : Taping

■ Shapes and Dimensions (Unit: mm)

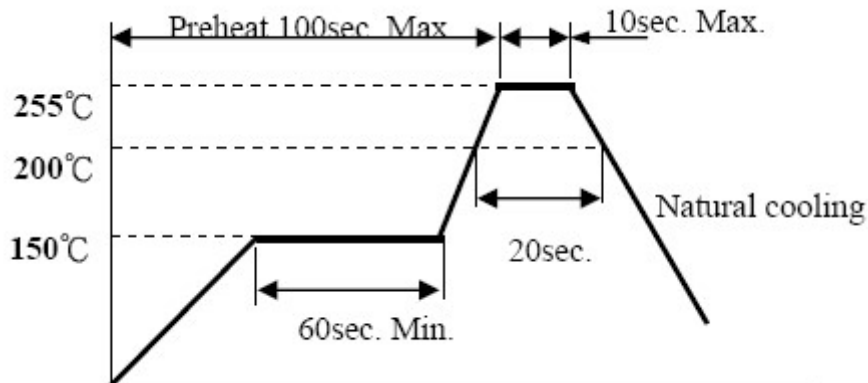


| TYPE | A | B | C | D | E | F | G | H | I | J |
|---------|---------|---------|---------|----------|----------|----------|------|------|------|------|
| YLM3225 | 3.2±0.2 | 2.5±0.2 | 2.2±0.2 | 0.90±0.1 | 0.80±0.1 | 0.80±0.1 | 0.90 | 2.50 | 2.20 | 4.00 |

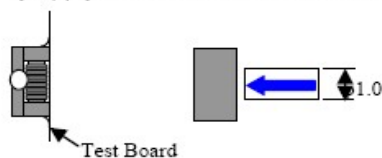
■ YLM3225 Series

| Part Number | Common mode Impedance (Ω) @100MHz | DC Resistance (Ω) Max | Rated Current (mA) max | Rated Volt. (Vdc)max. | Withstand Volt.(Vdc)max. | IR(MΩ) min. |
|---------------|-----------------------------------|-----------------------|------------------------|-----------------------|--------------------------|-------------|
| YLM3225□-900T | 90±25% | 0.05 | 1000 | 50 | 125 | 10 |
| YLM3225□-161T | 160±25% | 0.15 | 480 | 50 | 125 | 10 |
| YLM3225□-271T | 270±25% | 0.25 | 450 | 50 | 125 | 10 |
| YLM3225□-601T | 600±25% | 0.20 | 1000 | 50 | 125 | 10 |
| YLM3225□-102T | 1000±25% | 0.30 | 400 | 50 | 125 | 10 |

Recommended soldering temp.Graph



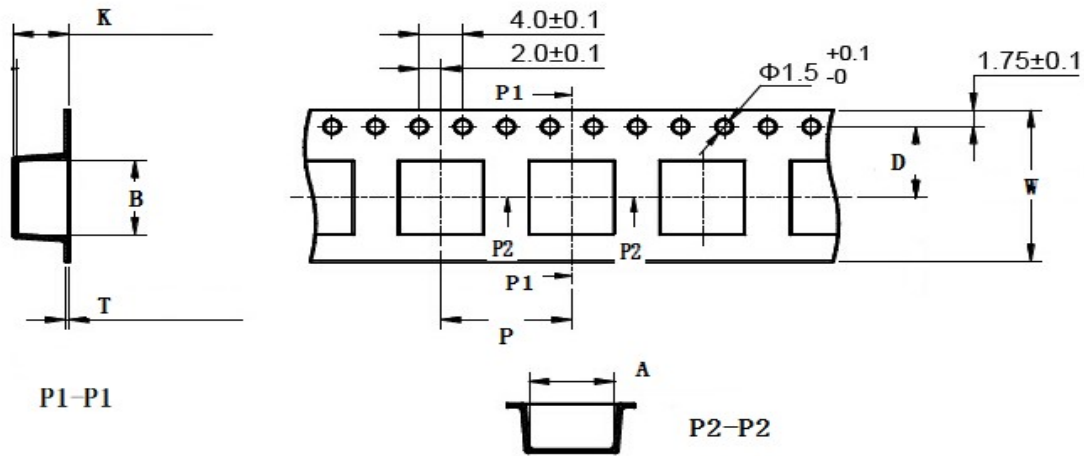
Mechanical reliability

| TEST | Specification & Requirement | Method Used |
|------------------------|--|---|
| Solderability | The surface of terminal/pin tested shall be covered with new solder by 90% | Solder heat proof: Preheating: 150 ±10°C 60 seconds Soldering: 230 ±5°C for 3 ±1 sec |
| Solder Heat Resistance | Components should have not evidence of electrical and mechanical damage Impedance: within ±15% of initial value | Preheating: 150°C 60secs Solder temperature: 260±5°C Flux: rosin Dip time: 10±0.5 secs |
| Terminal strength | Series No. | F (Kg) |
| | YLM2012 | 0.5 |
| | YLM3216/3225 | 1.0 |
| | YLM4532 | 1.5 |
| | | Solder a chip to test substrate and then laterally apply a force in the arrow direction  |

Endurance Reliability

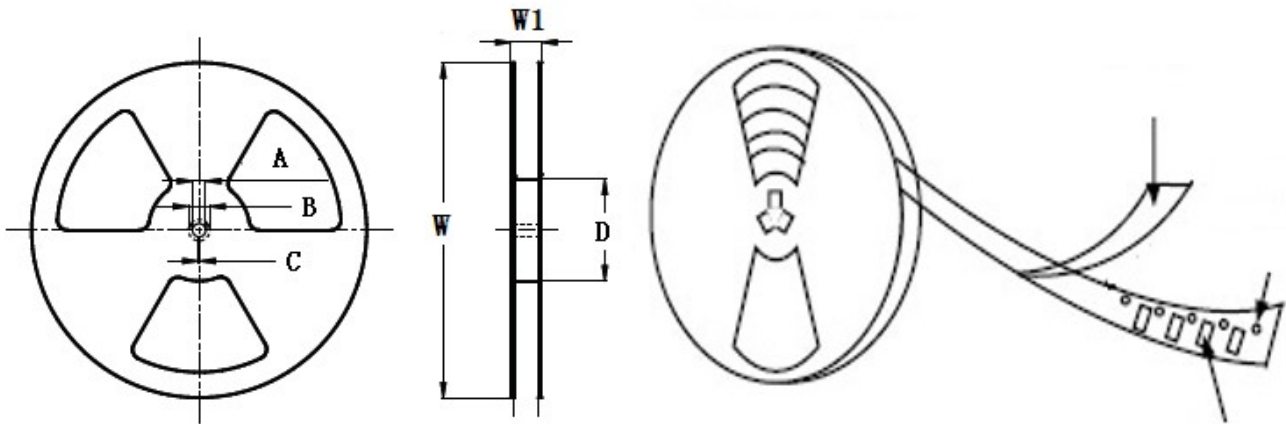
| TEST | Specification & Requirement | Method Used |
|---------------------|---|---|
| Thermal Shock | Impedance change within ± 15% Without mechanical damage | -25°C, (30 mins) -> room temp. (5 mins) -> 125°C, (30 mins) -> room temp. (5 mins) 10 cycles |
| Humidity Resistance | Impedance change within ± 15% Without mechanical damage | Apply IDC current @ 60°C ambient Humidity: 80% Duration: 168 hrs |
| Low Temp. Storing | Impedance change within ± 15% Without mechanical damage | Storing Temp. -25 ±2 °C for total 168 +5/-0 hours |
| High Temp. Storing | Impedance change within ± 15% Without mechanical damage | Storing Temp. 125 ±2 °C for total 168 +5/-0 hours |

■ Taping Dimensions(Unit:mm)



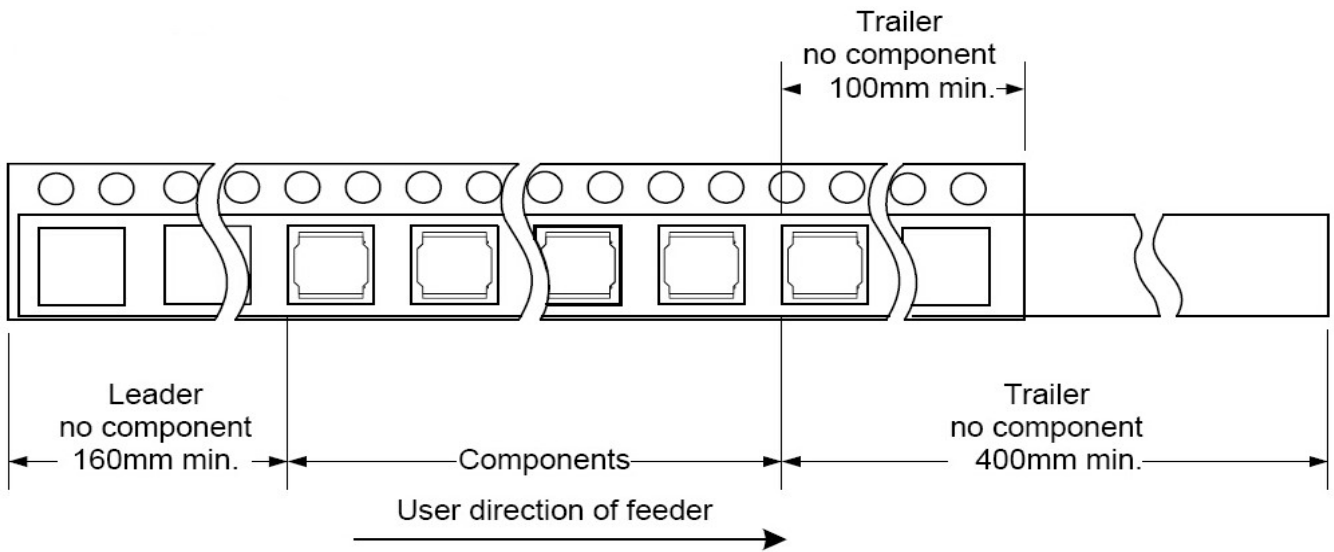
| TYPE | W | A | B | D | P | K | T | MPQ |
|---------|---------|----------|----------|----------|---------|----------|-----------|------|
| YLM3225 | 8.0±0.2 | 2.88±0.1 | 3.65±0.1 | 3.5±0.05 | 4.0±0.1 | 2.50±0.1 | 0.26±0.05 | 2000 |

■ Reel Dimensions(Unit:mm)

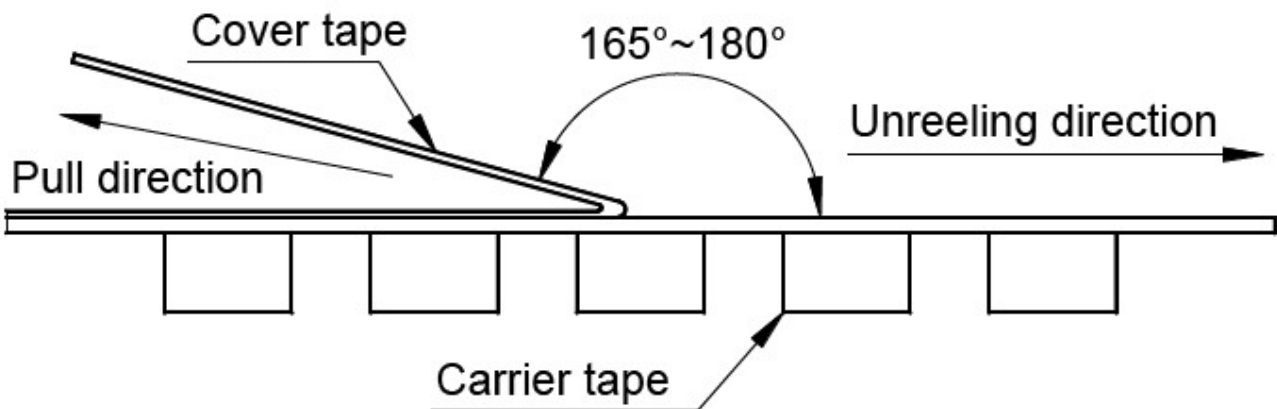


| TYPE | W | W1 | A | B | C | D |
|---------|---------|-----------|----------|----------|----------|--------|
| YLM3225 | 178±2.0 | 9.00±0.50 | 4.3±0.20 | 5.0±0.10 | 3.0±0.10 | 60±2.0 |

Direction of rolling



Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300 ± 10 mm/min.